

## Ultrasoft Recovery Bridge

### Features

Ultrasoft recovery

low  $I_{RRM}$

low VF

$V_{RRM}$

Special frame design for heat dissipation

Reduced EMI

Reduced snubbing

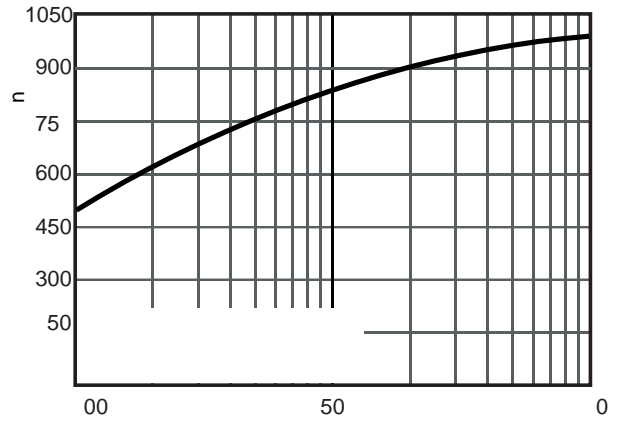
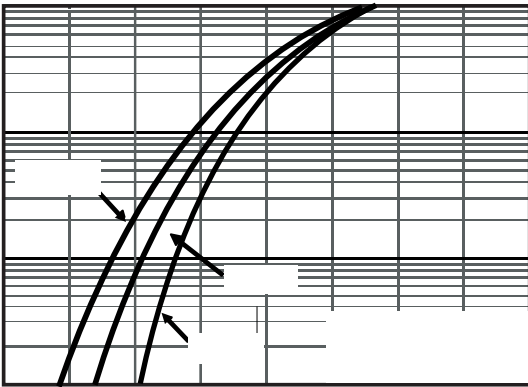
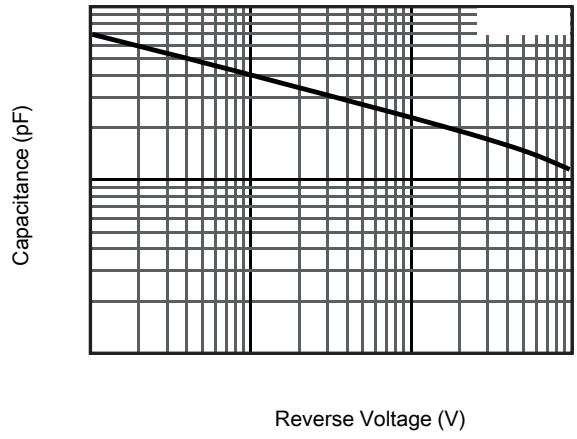
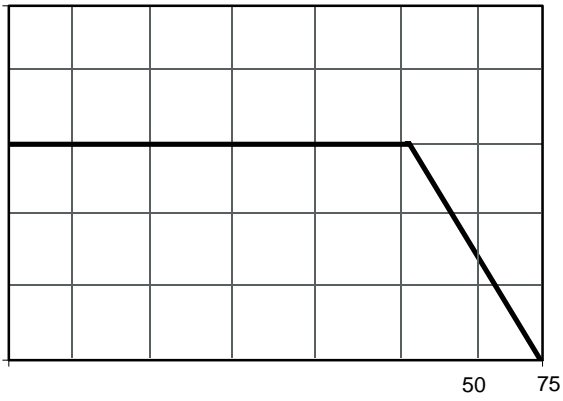
Input Pin ( ~ )
Input Pin ( ~ )
Output ( + )
Output ( - )

°

		XBS30J	XBS30K	XBS30M	
			3		
Reverse Recovery Time:IF=0.5A,IR=1A,IRR=0.25A	$T_{rr}$		10		us
			1		
$I^2 t$ rating for fusing ( F { • L A L A 10 { • )	$I^2 t$				A <sup>2</sup> S
1.5			0		
( )			4		
			75		°
2			6 12		

Thermal resistance from Junction to case,lead and ambient in accordance with JESD-51.  
Unit mounted on 15mm\*12mm\*1.6mm AL pad attach 195mm\*195mm\*10mm steel plate

**RATINGS AND CHARACTERISTICS CURVES**



# PACKAGE OUTLINE DIMENSIONS

